



WHM0003BE

10- 1000 MHz LOW NOISE WIDE BAND AMPLIFIER

REV B
September 2015

Key Features



- 50 Ohm Impedance
- 10 – 1000 MHz
- 0.8 dB Noise Figure
- 28.0 dBm Min Output IP₃
- 21.0 dB Gain
- +/-0.5 dB Gain Flatness
- 16.0 dBm P_{1dB}
- 1.35:1 VSWR Fully Matched
- +24 dBm Max Input CW Power
- >300 Years MTBF
- RoHS Compliance
- MSL-1 Moisture Sensitivity Level

Product Description

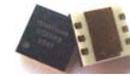
WHM0003BE is integrated with WanTcom proprietary low noise amplifier technologies, high frequency micro electronic assembly techniques, and high reliability designs to achieve optimum low noise figure, wideband, and high performances together. With single +3.3V DC operation, the amplifier has optimal input and output matching in the specified frequency range at 50-Ohm impedance system. The amplifier has standard 0.25" x 0.25" x 0.07" surface mount package.

The amplifier is designed to meet the rugged standard of MIL-STD-883g.



Applications

- Mobile Infrastructures
- Cellular
- VHF & UHF
- Defense
- Security System
- Measurement
- Fixed Wireless
- Avionics



Specifications

Summary of the key electrical specifications at room temperature

Index	Testing Item	Symbol	Test Constraints	Min	Nom	Max	Unit
1	Gain	S ₂₁	20 – 600 MHz	19.0	21.0		dB
2	Gain Variation	ΔG	20 – 600 MHz		+/-0.5	+/-1.0	dB
3	Input Return Loss	S ₁₁	20 – 600 MHz	14.0	16.0		dB
4	Output Return Loss	S ₂₂	20 – 600 MHz	14.0	16.0		dB
5	Reverse Isolation	S ₁₂	20 – 600 MHz	16.0			dB
6	Noise Figure	NF	50 – 600 MHz		0.70	1.0	dB
			20 – 50 MHz		0.90	1.4	
7	Output Power 1dB Compression Point	P _{1dB}	20 – 600 MHz	13.0	16.0		dBm
8	Output-Third-Order Interception Point	IP ₃	Two-Tone, P _{out} = 0 dBm each, 1 MHz separation	26.0	29.0		dBm
9	Current Consumption	I _{dd}	V _{dd} = +3.3 V		40		mA
10	Power Supply Operating Voltage	V _{dd}		+3.0	+3.3	+3.6	V
11	Thermal Resistance	R _{th,c}	Junction to case			215	°C/W
12	Operating Temperature Range	T _o		-40		+85	°C
13	Maximum Input CW RF Power	P _{IN, MAX}	DC – 6.0 GHz			24.0	dBm

Absolute Maximum Ratings

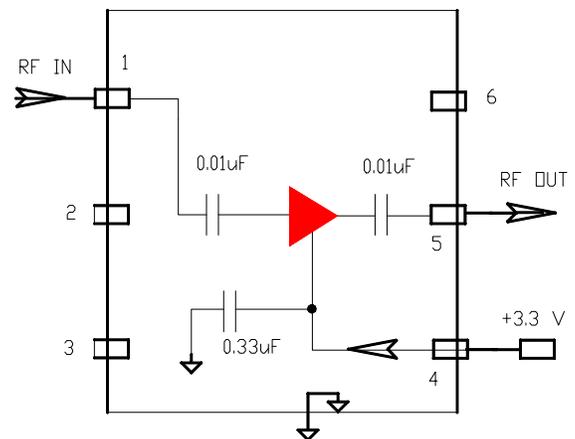
Parameters	Units	Ratings
DC Power Supply Voltage	V	-0.5 ~ +5.0
Drain Current	mA	70
Total Power Dissipation	mW	150
Input CW RF Power	dBm	24
Channel Temperature	°C	150
Storage Temperature	°C	-65 ~ 150
Operating Temperature	°C	-55 ~ +100
Thermal Resistance	°C/W	215

Operation of this device beyond any one of these parameters may cause permanent damage.

Ordering Information

Model Number	WHM0003BE
--------------	-----------

Functional Block Diagram



Specifications and information are subject to change without notice.



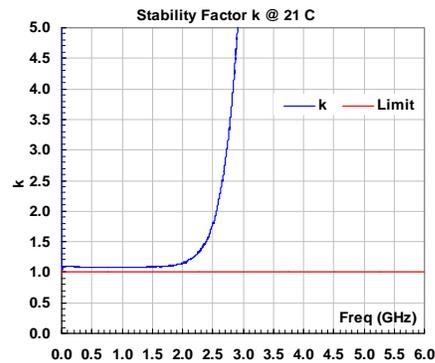
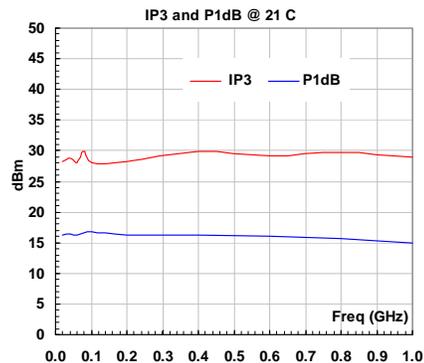
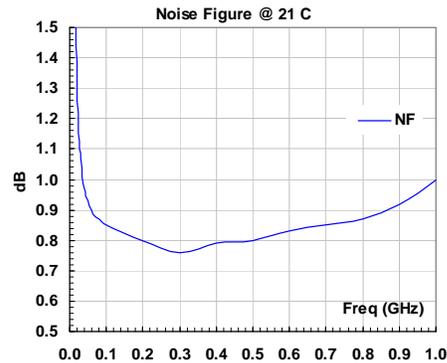
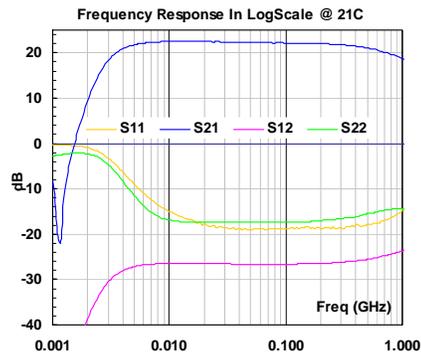
WHM0003BE

10- 1000 MHz LOW NOISE WIDE BAND AMPLIFIER

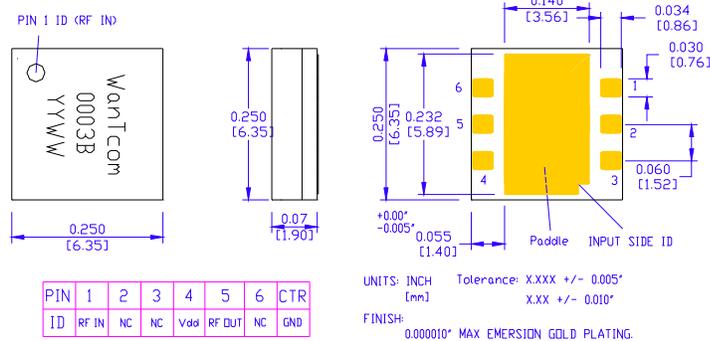
REV B
September 2015

ESD tube with the capacity of 25 pieces is used for the packing. Contact factory for tape and reel packing option for higher volume order.

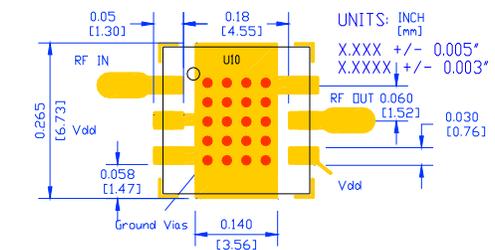
Typical Data



Outline



Foot Print/Motherboard Layout



- NOTE:
1. THE BACKSIDE NEEDS TO BE METAL GROUND LAYER
 2. GROUND VIA DIAMETER IS 0.024" (0.61 mm);
 3. C1 IS 0.01 UF OR LARGER VALUE CAPACITOR
 4. MATERIAL: FR-4, 4000-13, or RD4003, etc.
 5. USE PROPER WIDTH FOR 50-OHM LINES FOR OTHER PCB MATERIAL

Specifications and information are subject to change without notice.



Application Notes:

A. Motherboard Layout

The similar motherboard layout example is shown in **Figure 1**. Sufficient numbers of ground vias on center ground pad are essential for the RF grounding. The width of the 50-Ohm microstrip lines at the input and output RF ports may be different for different property of the substrate. The ground plane on the backside of the substrate is needed to connect the center ground pad through the vias. The ground plane is also essential for the 50-Ohm microstrip line launches at the input and output ports.

The +3.3V DC voltage is applied at Pin 4. For +3.3V line trace length being longer than 6 inches without a decoupling capacitor, a 0.1 uF de-coupling capacitor, C_1 , with minimum rating voltage of 6.3V is needed across the +3.3V pin to ground. The capacitor must be rated in the temperature range of -55°C to 100°C to ensure the entire circuit work in the specified temperature range.

No DC block capacitor is required at input and output RF ports. The NC pins connected to ground are recommended.

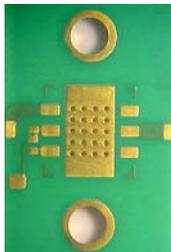


Fig. 1 Motherboard foot print

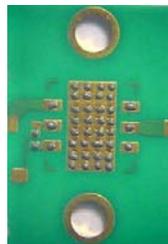


Fig. 2 Dispensed solder paste

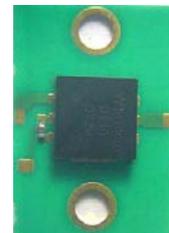


Fig. 3 Assembled part

B. Assembly

The regular low temperature and none clean solder paste such as SN63/Pb37 is recommended. The high temperature solder has been used internally for the WHM series amplifier assembly. The melting temperature point of the high temperature solder is around 240°C . Thus, melting temperature of the solder paste should be below 220°C for assembling WHM series amplifier on the test board to reduce the possible damage. The temperature melting point of the SN63/Pb37 solder paste is around 183°C and is suitable for the assembly purpose.

The SN63/Pb37 solder paste can be dispensed by a needle manually or driven by a compressed air. **Figure 2** shows the example of the dispensed solder paste pattern. Each paste dot is in the diameter of $0.005'' \sim 0.010''$ ($0.125 \sim 0.250$ mm).

For volume assembly, a stencil with $0.004''$ (0.10 mm) is recommended to print the solder paste on the circuit board.

For more detail assembly process, refer to AN-109 at www.wantcominc.com website.

C. Electrical Testing and Fine Tuning

The amplifier is designed to be fully matched at the input and output ports. Any tuning is not needed. However, when connecting the assembled amplifier to a device such as a SMA connector or a filter, the connecting point or joint point could affect mainly the return loss at the port due to the non-ideal 50-Ohm impedance of the device. By varying the connection feature size such as the solder amount to get the optimum return loss or best matching result at the interface. This fine-tuning has little affect on the other performance such as gain, noise figure, P_{1dB} , or IP_3 .

During the fine-tuning process, a vector network analyzer can be used to monitoring the return loss at the port while varying the feature size of the joint point. Varying the connection feature size until the optimum return loss is achieved.
